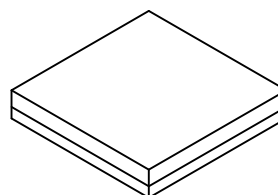




REV.	DESCRIPTION	DATE	CHANGED	CHANGED BY
00	INITIAL RELEASE PER DCN# C08694	01/14/98	E.B.	JW
01	UPDATED TO STANDARDS. DCN C04486	08/88/98	E.B.	HLE



7. REFERENCE SPECIFICATIONS:
- A. AAWF SPEC #001-0581-2294: PACKING OPERATION PROCEDURE.
  - B. AAWF SPEC #001-0519-5068: MARKING.
8. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
9. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BUMPS IS 36.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 6 X 6.
2. THE BASIC SOLDER PUMP GRID PITCH IS 0.50.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS DECIMAL 2.5 25.0 3.18 31.8 5.08 50.8		 ANGULAR 2°		AMM Industrial Co., Ltd. Singapore 30, Selet, Narve		AMM Electronics, Inc. Cheshire, Arkansas, USA			
APPROVALS BY J. TRENEY DATE 01/06/90 BY R. CANTRELL DATE 01/06/90 BY T. PARSONS DATE 01/06/90 DESIGNED APPROVED DATE 01/06/90		DATE 01/06/90 DATE 01/06/90 DATE 01/06/90 DATE 01/06/90		THIS DRAWING IS THE PROPERTY OF AMM INDUSTRIAL CO., LTD. IT IS TO BE USED FOR THE PROJECT AND NOT FOR OTHER PURPOSES SCALE: 8:1 SHEET 1 OF 1					